

MBR3060CT
Rev.H Oct.-2018

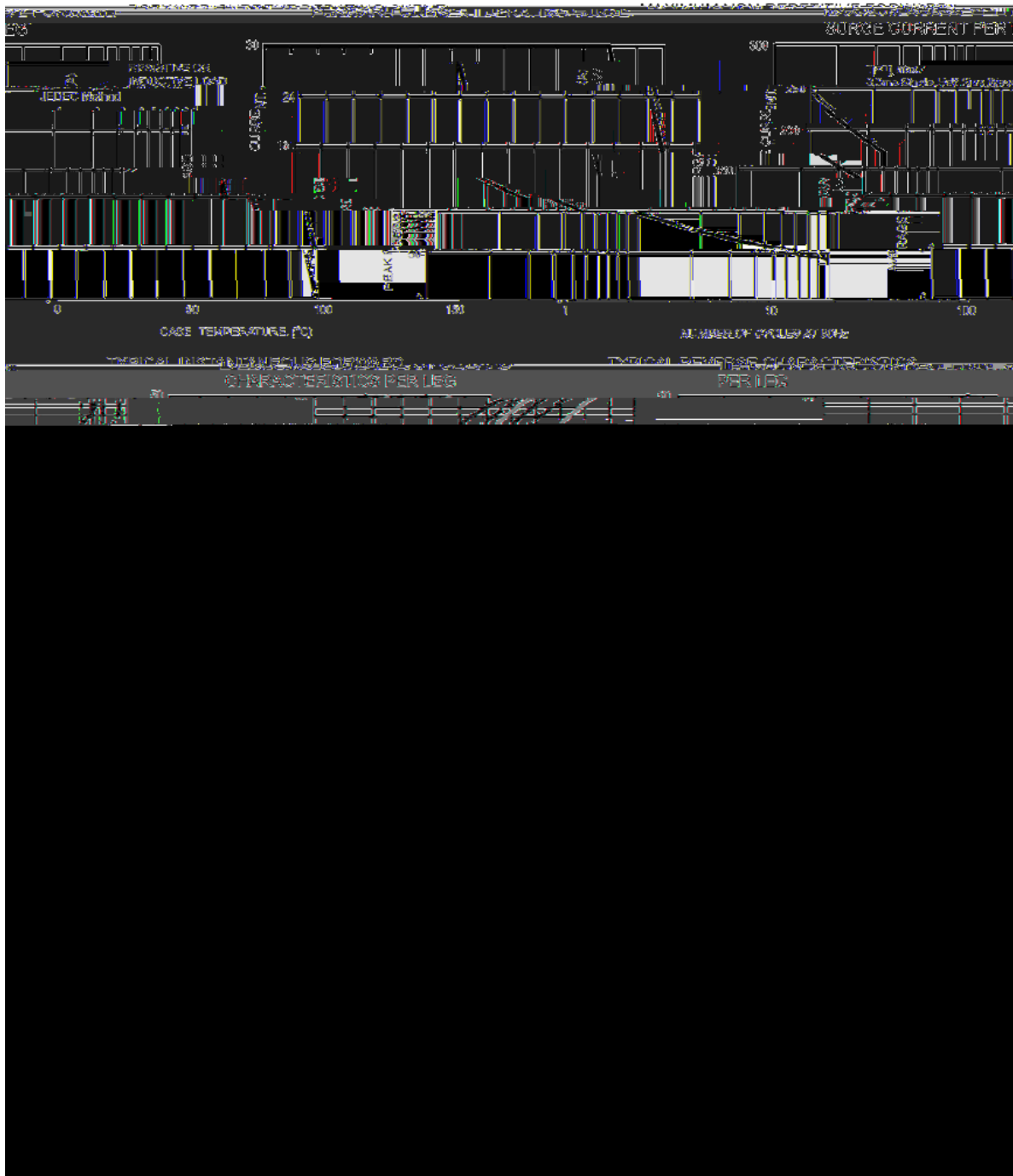
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	60	V
RMS Voltage	V_{RMS}	42	V
DC Blocking Voltage	V_{DC}	60	V
Peak Repetitive Forward Current	$I_{F(AV)}$	15	A
	$I_{F(AV)}$ 15F9tal device	30	A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	250	A
Peak Forward Surge Current	I_{FRM}	30	A
Repetitive Peak Reverse Surge Current	I_{RRM}	0.5	A
Thermal Resistance Junction to Case	R_{JC}	1.0	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

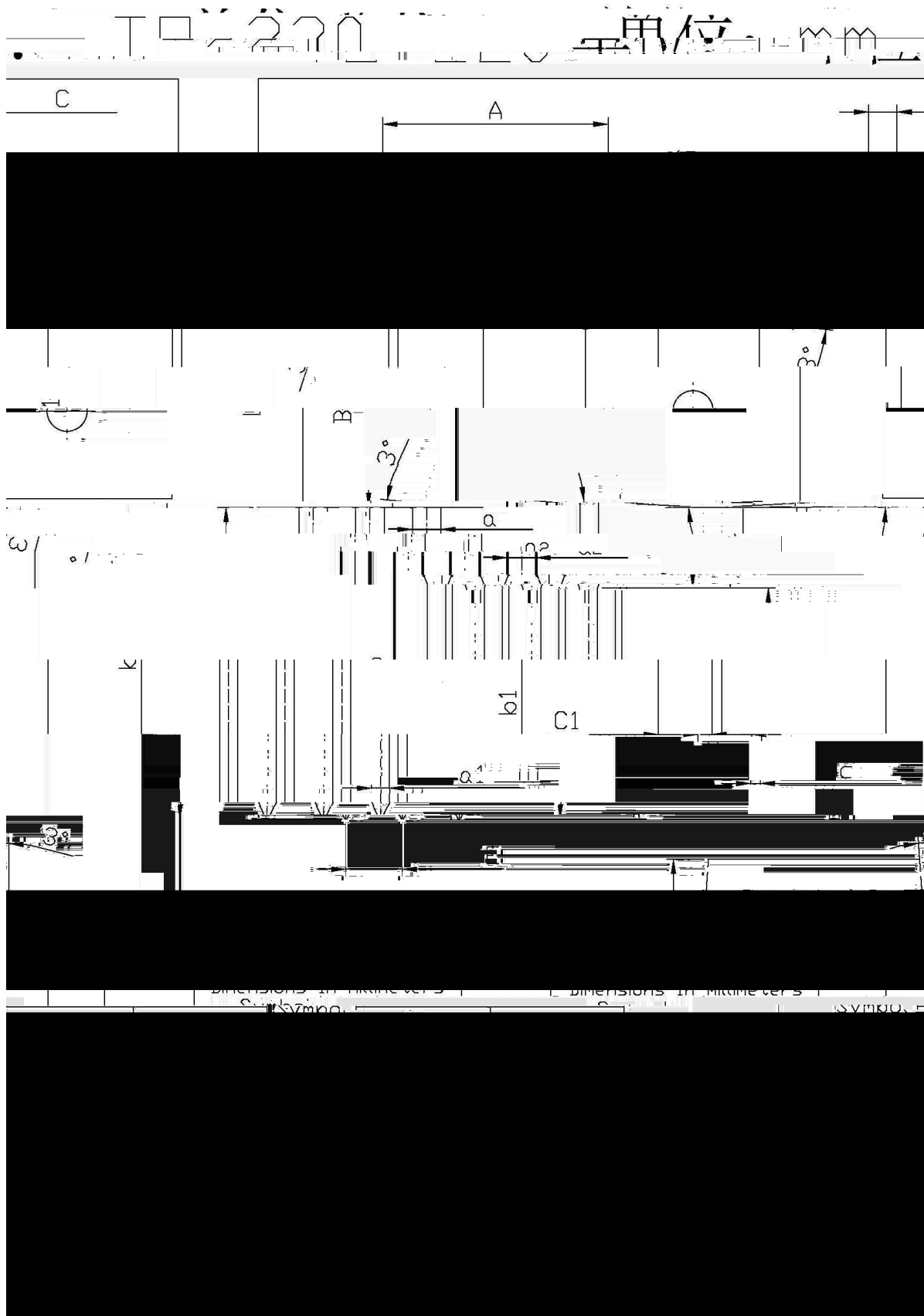
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=15A(T_C=25)$			0.75	V
		$I_F=15A(T_C=125)$			0.65	V
		$I_F=30A(T_C=25)$			0.95	V
		$I_F=30A(T_C=125)$			0.85	V
Instantaneous Reverse Current	I_R	$T_C=25$			0.2	mA
		$T_C=125$			50	mA
Voltage Rate of Change	dv/dt				1000	V/ s

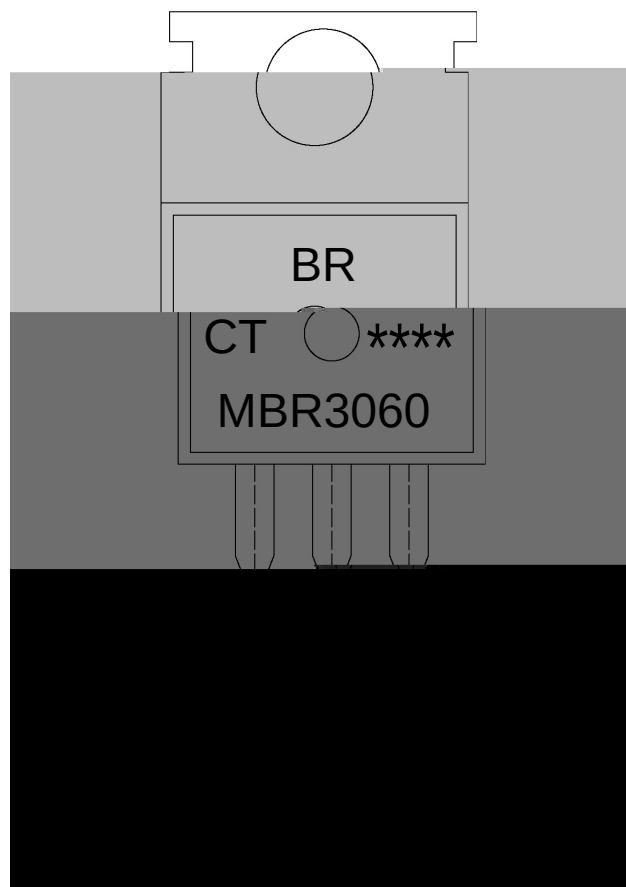
/ Electrical Characteristic Curve



/ PackageDimensions



/ Marking Instructions



BR

MBR3060

CT:

Note:

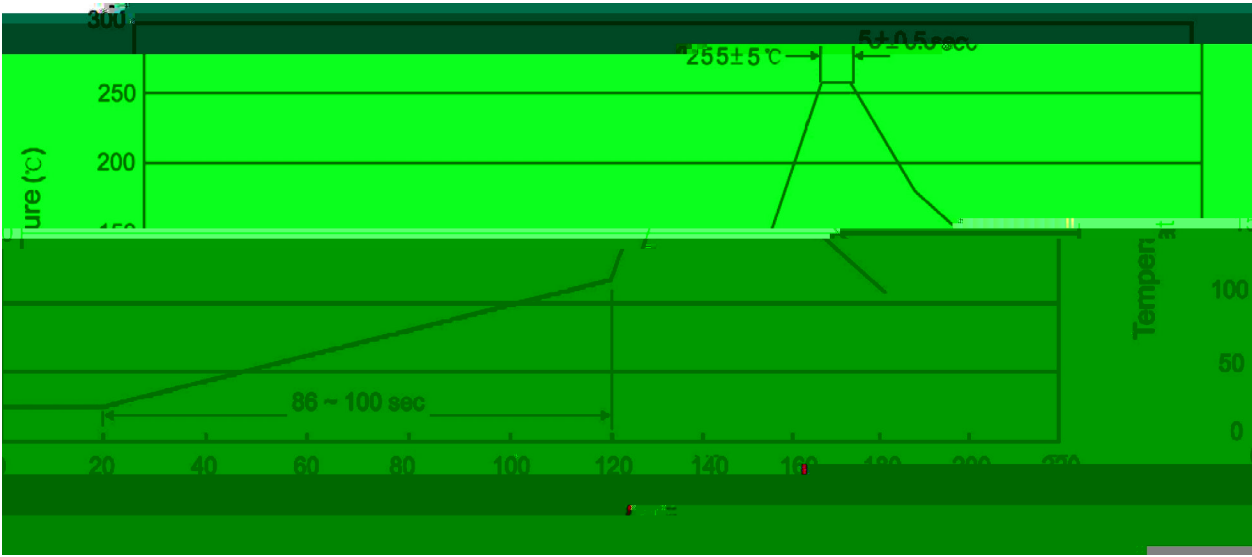
BR: Company Code

MBR3060 Product Type.

CT: Internal Structure

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:255±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension			(unit mm ³)
	Units/Bag	Bags/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Bag	Inner Box	Outer Box	